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material to be silicided comprises titanium.

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*Fig 1*  
24. (Three Times Amended) A method for fabricating a semiconductor device,  
comprising:

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providing a semiconductor substrate which has a silicon region located on an

insulating layer formed in the semiconductor substrate;

forming a metal layer on the silicon region of the semiconductor substrate;

performing a first rapid thermal annealing on the semiconductor substrate to  
form first-reacted silicide regions;

forming a supplemental silicon layer on the first-reacted silicide regions;

doping an impurity into the supplemental silicon layer; and

performing a second rapid thermal annealing to convert the first-reacted silicide  
regions into second-reacted silicide regions, by reaction of the supplemental silicon  
layer with the first-reacted silicide regions,

the semiconductor device including a p-channel MOS transistor having p-type  
source and drain diffusion layers, and including an n-channel MOS transistor having n-  
type source and drain diffusion layers,

said doping comprising doping the impurity into the supplemental silicon layer so  
that only the supplemental silicon layer formed over the p-channel MOS transistor is  
doped, or so that only the supplemental silicon layer formed over the n-channel MOS  
transistor is doped.

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30. (Amended) A method for fabricating a semiconductor device comprising:

providing a silicon substrate;

providing a buried oxide layer on the silicon substrate;

providing a field oxide layer and a silicon on insulator layer on the buried oxide layer;

providing a gate oxide layer on the silicon on insulator layer;

providing a poly-silicon gate layer on the gate oxide layer;

providing a gate side wall layer on the silicon on insulator layer to surround the poly-silicon gate layer and the gate oxide layer;

providing a material to be silicided on a surface of the semiconductor device including the poly-silicon gate layer, the gate side wall layer, the silicon on insulator layer and the field oxide layer;

performing a first rapid thermal annealing process to form first-reacted silicide regions in the poly-silicon gate layer and in source/drain active areas of the silicon on insulator layer;

removing non-reacted material from the first-reacted silicide regions;

providing a supplemental silicon layer over the surface of the semiconductor device after the non-reacted material is removed;

doping the supplemental silicon layer; and

performing a second rapid thermal annealing process to convert the first-reacted silicide regions into second-reacted silicide regions, by reaction of the supplemental

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silicon layer with the first-reacted silicide regions,

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the supplemental silicon layer preventing the poly-silicon gate layer and the silicon on insulator layer from being completely silicided,

the semiconductor device including a p-channel MOS transistor having p-type source and drain regions, and including an n-channel MOS transistor having n-type source and drain regions,

said doping comprising doping an impurity into the supplemental silicon layer so that only the supplemental silicon layer provided over the p-channel MOS transistor is doped, or so that only the supplemental silicon layer provided over the n-channel MOS transistor is doped.

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Please add claims 31-34 as follows:

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--31. The method according to claim 24, wherein said doping comprises doping a p-type impurity into the supplemental silicon layer so that only the supplemental silicon layer over the p-channel MOS transistor is doped p-type.

32. The method according to claim 24, wherein said doping comprises doping an n-type impurity into the supplemental silicon layer so that only the supplemental silicon layer over the n-channel MOS transistor is doped n-type.

33. The method according to claim 30, wherein said doping comprises doping a

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p-type impurity into the supplemental silicon layer so that only the supplemental silicon layer over the p-channel MOS transistor is doped p-type.

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34. The method according to claim 30, wherein said doping comprises doping an n-type impurity into the supplemental silicon layer so that only the supplemental silicon layer over the n-channel MOS transistor is doped n-type.--

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